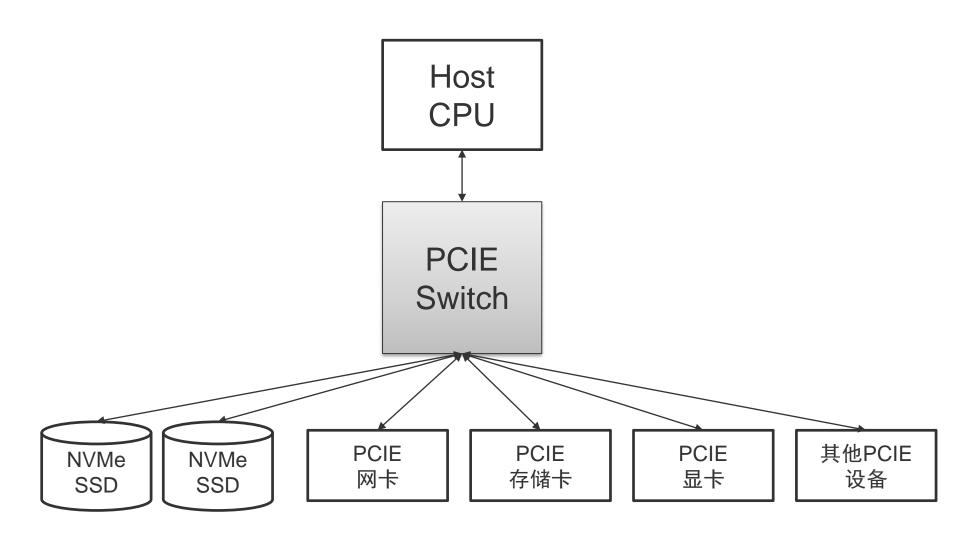


利用PCIE Switch+RDMA技术加速数据中心IO流量

张冬 高级资深数据中心架构师dong.zhang@Microsemi.com

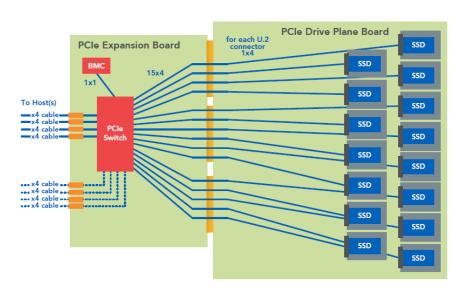
PCIE Switch能做什么——FANOUT

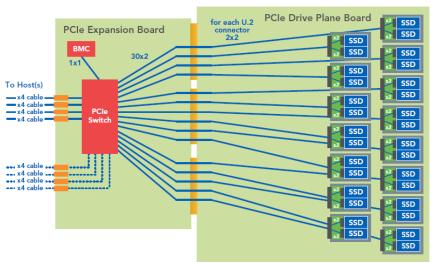




单芯片最大支持48个Port——Microsemi特有

PCle switch configurations





15 x4 SSDs

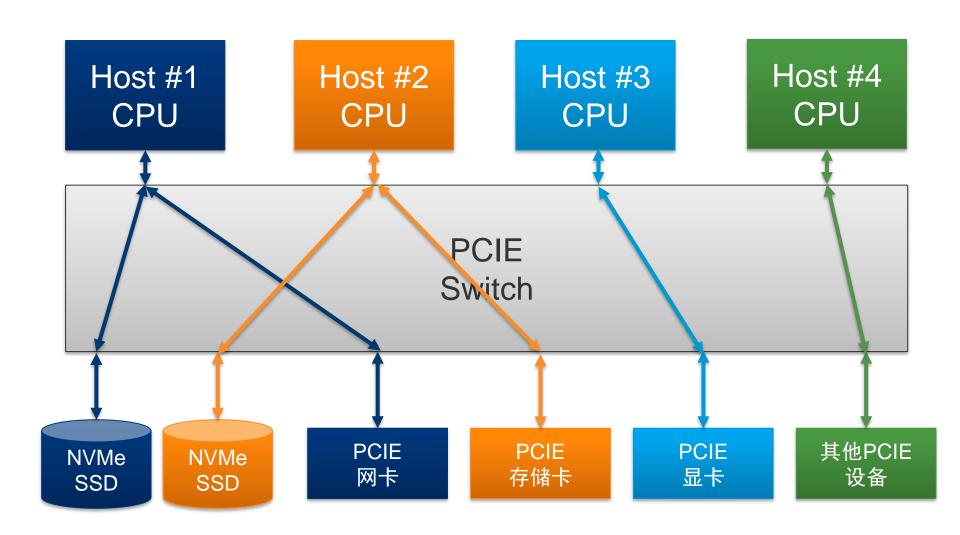
30 x2 SSDs

Open Compute (Facebook) Reference Design

http://www.opencompute.org/wiki/Storage (search for Lightning)

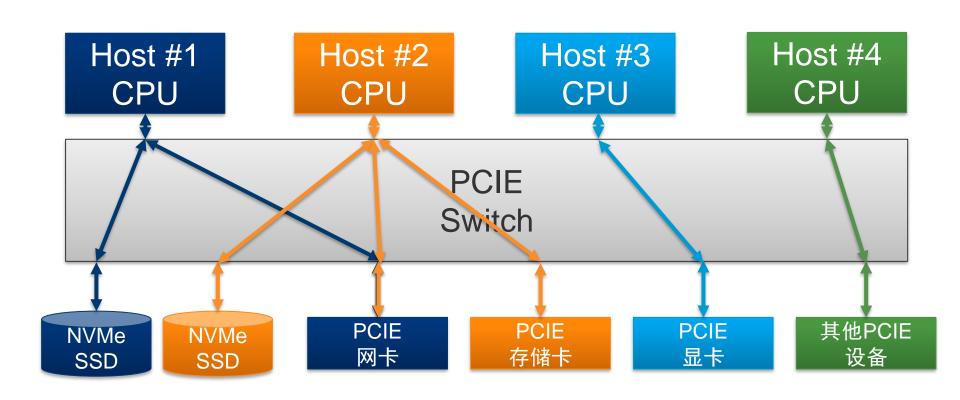


PCIE Switch能做什么——分区





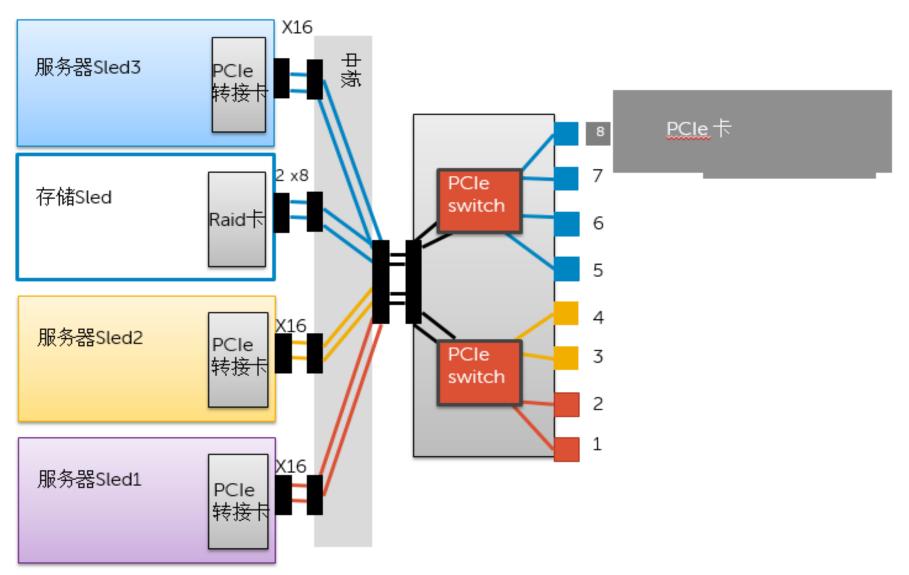
动态分区——Microsemi PCIE Switch特有



分区的重新配置不需要主机端重启,不中断主机端原有的IO访问。新添加设备动态发现并理解可用。

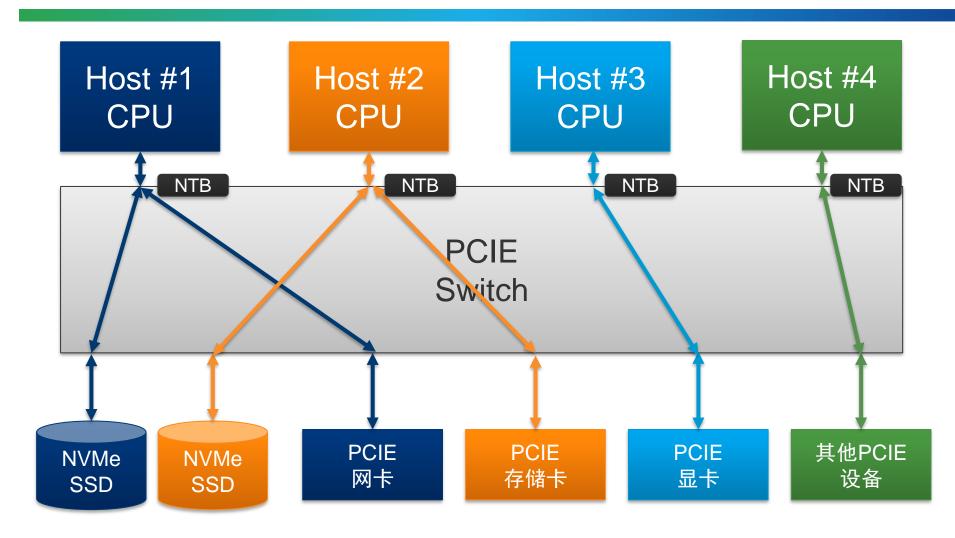


基于PCIE Switch分区的服务器设计





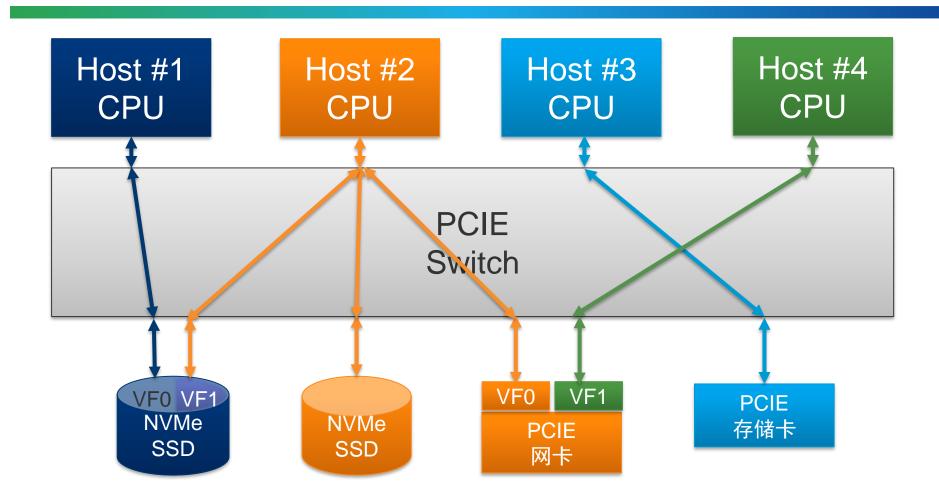
PCIE Switch能做什么——多机互联



Microsemi PCIE Switch最大支持48台主机互联



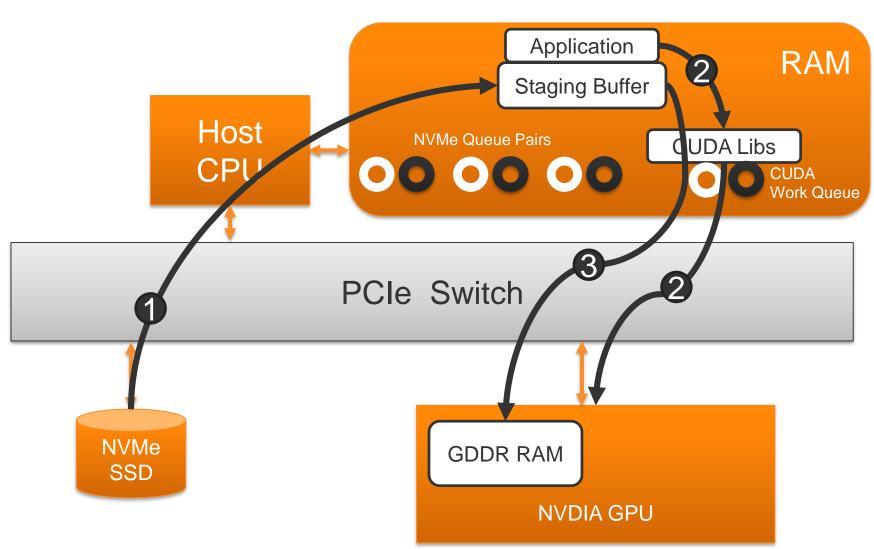
PCIE Switch能做什么——共享IO



将支持SRIOV的PCIE设备透明转换为MRIOV模式

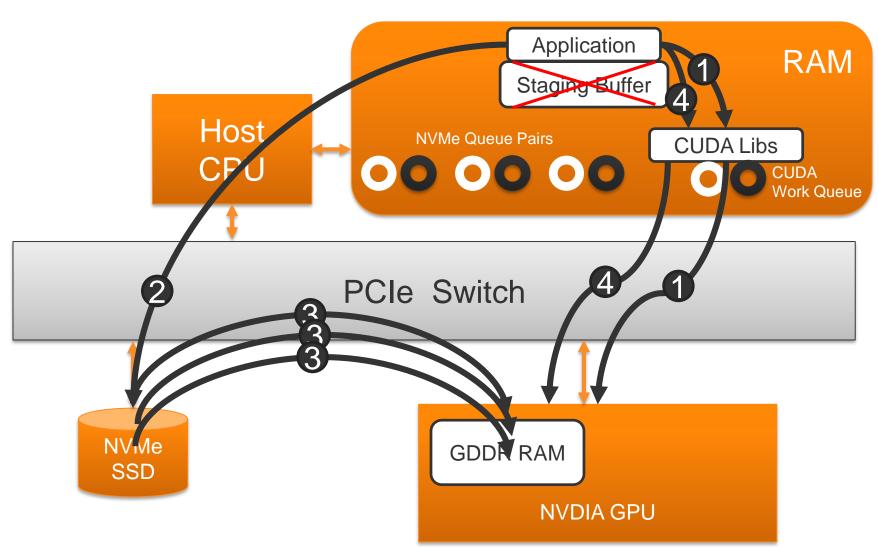


PCIE Switch能做什么——P2P传输





PCIE Switch能做什么——P2P传输





利用P2P GPU Direct加速图像搜索过程

数据读取速度	带宽(GB/s)	主机RAM相对使用率
传统做法	1.90	5230
P2P	2.50	1

图像处理速度	HDD	SDD	
	兆像素/秒	兆像素/秒	瓶颈点
CPU	77.0	122.8	CPU
CUDA	95.1	312.5	DRAM
P2P	N/A	534.2	GPU



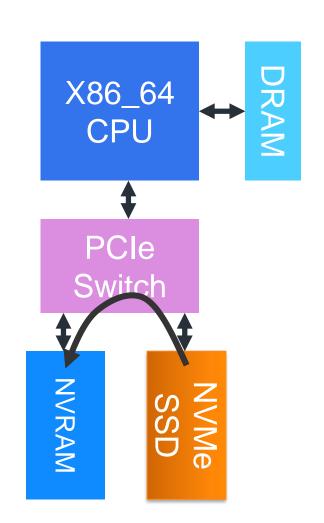
实现P2P传输的条件

- 支持将MMIO BAR注册为DAX块设备的Linux内核。 Microsemi开发了参考代码,对Linux内核有88行的变更。从 而可支持将 DAX设备地址空间作为DMA的源端。
- CUDA 6.0 以上版本, 支持GPU Direct P2P传输
- 将DMA过程中的get_user_pages(), 以及put_pages()下游代 码进行变更。通过对应的DAX设备的IOCTRL 下发P2P DMA 传输。#define NVME_IOCTL_SUBMIT_GPU_IO _IOW('N', 0x45, struct nvme_gpu_io)



应用场景: NVMe SSD <-> NVRAM

- NVRAM作为写缓存,NVMe SSD 直接从NVRAM中读取数据并写入 Flash, bypass本地CPU
- 可以使用NVRAM DAX设备提供 的mmap()将文件映射到NVRAM 锁对应**的内存区域**,NVMe SSD 直接读写该区域。

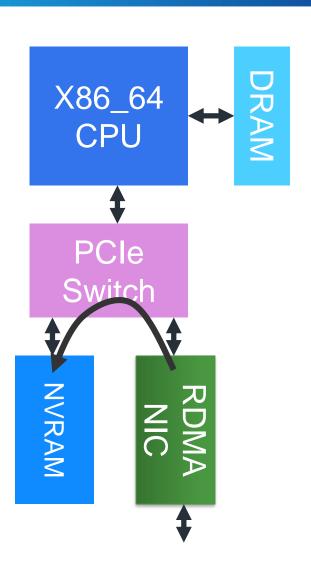




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应用场景: RDMA NIC <-> NVRAM

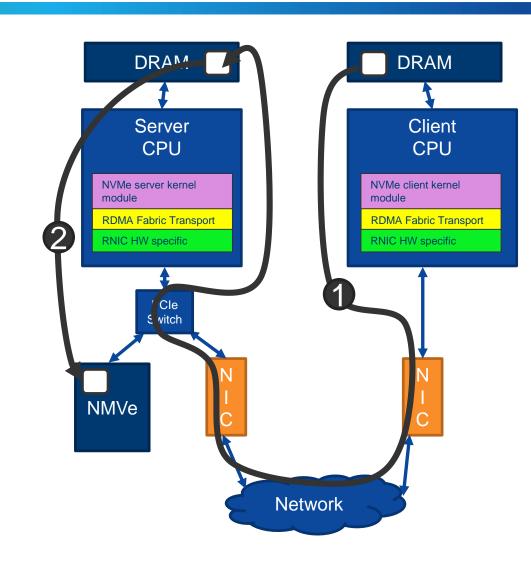
- 对端主机向本端NVRAM直接推送 数据,数据传送过程bypass两端的 **CPU**
- 可以使用NVRAM DAX设备提供的 mmap()将文件映射到对应的内存 区域. 对端RDMA访问本端文件





应用场景: NVMe over Fabric with RDMA

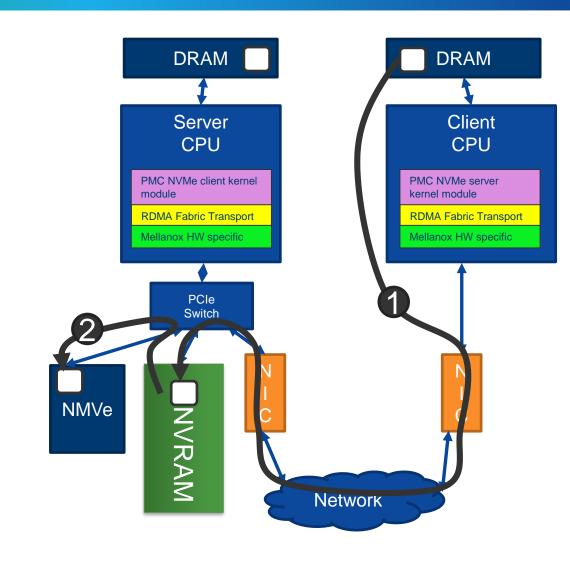
- NVMe Initiator端与Target端预 先注册好双方各自的Memory Region, 将对应的NVMe Queue映射到RNIC的Queue Pair. 采用RDMA交互指令及数 据.
- NVMe Target端程序接收到IO及 数据之后, 经过处理, 向本地 NVMe SSD发起IO读写请求。





应用场景: NVMEoF with RDMA & Cache & P2P

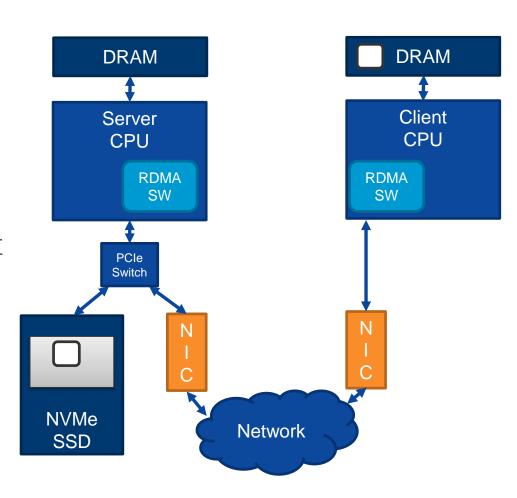
- NVMe Initiator端与Target端预先注 册好双方各自的Memory Region, 其中一方落入NVRAM空间。将对 应的NVMe Queue映射到RNIC的 Queue Pair、采用RDMA交互指令 及数据。
- NVRAM作为写缓存,可降低全固 态阵列的时延抖动。
- NVMe Target端程序接收到IO及数 据之后,向本地NVMe SSD发起IO 读写请求,在数据传输时,NVMe SSD直接从NVRAM中将数据读出, bypass CPU.





应用场景: NVMEoF with RDMA & CMB & P2P

- NVMe CMB作为RNIC的MR, 远 端将指令和数据直接通过RDMA 写入CMB。远端直接读写本地 NVMe盘。
- NVMe IO completion消息依然需 要本地代码处理。可以在NVMe盘 固件中做开发支持RDMA verb, 从而可bypass本地CPU。





Thank YOU!



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